IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1					Form Type ³ Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier Inforn	nation								,					
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2024-05-02			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Represe	entative*		Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requeste	Requester Item Number Mf		Mfr Item Number Mfr Item Name					Version	Manufacturing Site		1	Weight*	UOM	Unit Type
		MC74AC02DG LOG CMOS		LOG CMOS GATE	ATE NOR QUAD		2024-05-02		1	PH1		122.05	mg	Each
	Process Information											ļ., ,		
ž ž			•		STD-020 MSL	. Rating	Peak Process Body Temp			1			er of Reflow Cyc	eles
•	n (Sn) - annealed	C	U Alloy	1			260		C	30	secon	ds 3		
omments														
	ime at peak temperature													
or more informati	on regarding material co	mposition p	olease refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg
Die Attach	4.44	mg	Supplier	Silver (Ag)	7440-22-4		3.33	mg
			Supplier	Epoxy resins	129915-35-1		1.11	mg
Lead Frame	69.62	mg	Supplier	Silver (Ag)	7440-22-4		0.7658	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1392	mg
			Supplier	Iron (Fe)	7439-89-6		1.8101	mg
			Supplier	Copper (Cu)	7440-50-8		66.9048	mg
Mold Compound-Black	43.43	mg		Epoxy Phenol Resin	proprietary data		4.5601	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.8699	mg
Plating	3.27	mg	Supplier	Tin (Sn)	7440-31-5		3.27	mg
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg